

Amendments To The Claims:

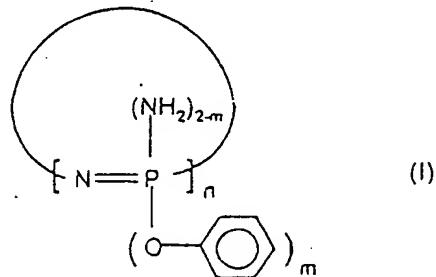
This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of claims:

1. (Presently Amended) A flame retarded epoxy resin composition coated on a substrate to form a dielectric material for a build-up process, which comprises:

(A) at least one type of epoxy resin; and

(B) a phosphorus-and-nitrogen-containing heterocyclic compound, said compound having a moiety which can is capable of reacting with an the epoxy group of the epoxy resin, is useful as a hardening agent for the epoxy resin, and having a structure as shown by formula (I):

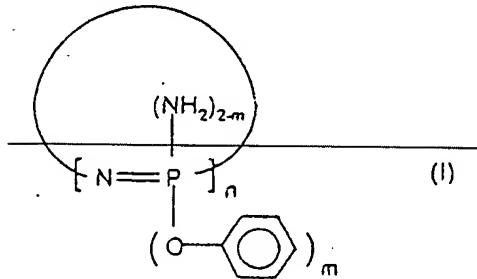


wherein m is an integer of from 0 to 2, n is an integer of from 3 to 7, but at least one occurrence of m in formula (I) is not 2.

2. (Presently Amended) The A flame retarded epoxy resin composition coated on a substrate to form a dielectric material for a build-up process which comprises according to claim 1, further comprising:

(A) at least one type of epoxy resin; and

(B) a phosphorus and nitrogen containing heterocyclic compound, said compound having a moiety which can react with the epoxy group of the epoxy resin, useful as a hardening agent for the epoxy resin, and having a structure as shown by formula (I):



wherein m is an integer of from 0 to 2, n is an integer of from 3 to 7, but at least one m is not 2; and

(C) a hardening agent, which does not contain phosphorus;

and selectively added:

(D) a hardening promoter;

(E) a solvent; and, additionally,

(F) additives.

3-20. (Cancelled).

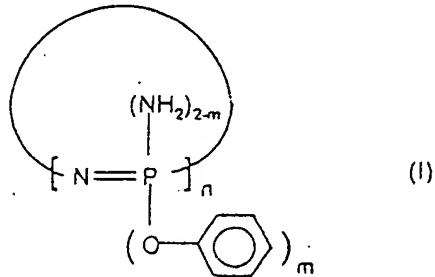
21. (Presently Amended) The flame retarded epoxy resin composition coated on a substrate to form a dielectric material for a build-up process according to claim 191, wherein the substrate used for making dielectric materials for the build-up process is copper foil or releasing film.

22-23. (Cancelled).

24. (New) The flame retarded epoxy resin composition coated on a substrate to form a dielectric material for a build-up process according to claim 2, wherein the substrate used for making dielectric materials for the build-up process is copper foil or releasing film.

25. (New) A prepreg comprising a reinforced substrate and a flame retarded epoxy resin composition, wherein the flame retarded epoxy resin composition comprises:

(A) at least one epoxy resin; and
(B) a phosphorus-and-nitrogen-containing heterocyclic compound, said compound having a moiety which is capable of reacting with an epoxy group of the epoxy resin, is useful as a hardening agent for the epoxy resin, and having a structure as shown by formula (I):



wherein m is an integer of from 0 to 2, n is an integer of from 3 to 7, but at least one occurrence of m in formula (I) is not 2.

26. (New) The prepreg of claim 25, wherein the flame retarded epoxy resin composition further comprises (C) a hardening agent, which does not contain phosphorus.

27. (new) The prepreg of claim 25, wherein the prepreg is laminated to form a laminate or laminated plate having flame retardancy and high heat resistance.

28. (new) The prepreg of claim 27, wherein the laminated prepreg further comprises a copper foil layer and is suitable for use in manufacturing of printed circuit boards.